MHz Range Crystal unit

• Package size (1.6 mm × 1.2 mm × 0.35 mm)

Fundamental mode

· Reference weight Typ.3.0 mg

[1] Product Number / Product Name / Marking

(1-1) Product Number / Ordering Code

X1E0002510009xx

Last 2 digits code(xx) defines Quantity.

The standard is "26", 6 000 pcs/Reel.

(1-2) Product Name / Model Name

FA-118T 27.120000 MHz 10.0 +30.0-30.0

[2] Absolute maximum ratings

Parameter	Svmbol	0,	Specification	S	Unit	Conditions	
Falameter	Symbol	Min.	Тур.	Max.	Unit		
Storage temperature	T_stg	-40	-	+125	°C	Storage as single product	
Operating temperature range	T_use	-40	-	+105	°C	-	

[3] Specifications(characteristics)

Parameter	Sumbol		Specifications	3	Unit	Conditions	
Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions	
Nominal frequency	f_nom	-	27.120000	-	MHz	Fundamental	
Frequency tolerance	f_tol	-30	-	+30	x 10 ⁻⁶	@+25°C	
Frequency Stability over temperature	f_tem	-50	-	+50	x 10 ⁻⁶	-20ºC to +75ºC	
Operating temperature	T_use	-20	-	+75	°C		
Level of drive	DL	10	-	100	μW	Recommended: 10 µW	
Load capacitance	CL	-	10	-	pF		
Motional resistance (ESR)	R1	-	-	200	Ω		
Motional capacitance	C1	-	1.14	-	fF		
Motional inductance	L1	-	30.21	-	mH		
Shunt capacitance	C0	-	0.44	-	pF		
Frequency aging	f_age	-5	_	+5	x10 ⁻⁶ /yea	@+25°C, First year	

[For other general specifications, please refer to the attached Full Data Sheet below]

1.6 x 1.2 mm size MHz range crystal unit: FA-118T

Features

- Package size: $1.6 \times 1.2 \text{ mm}$, t = 0.35 mm Max.
- Frequency range: 24 MHz to 54 MHz
- Frequency tolerance (standard): $\pm 10 \times 10^{-6} / \pm 30 \times 10^{-6} (@+25 °C)$
- Frequency vs. temperature characteristics (standard):

• ESR:

±30 x 10⁻⁶ (-20 °C to +75 °C) 200 Ω Max. (24 MHz <u><</u> f_nom < 32 MHz)

±12 x 10⁻⁶ (-20 °C to +75 °C)

100 Ω Max. (32 MHz \leq f_nom < 36 MHz)

80 Ω Max. (36 MHz <u><</u> f_nom <u><</u> 54 MHz)

Applications

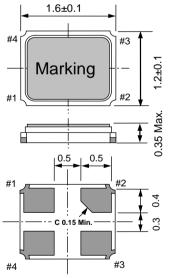
- Small communication module for consumer and industrial applications
- Wearable devices
- Clock for MCU

Description

The FA-118T has been commercialized as a reference clock for communication modules, which requires high accuracy, and as a clock for wireless communication and microcomputers for applications that require miniaturization (TWS (True Wireless Stereo), Smart Watch, etc.).

The products created using the high-precision processing technology cultivated over many years contribute to improving the performance of the customer's system.

Outline Drawing and Terminal Assignment



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Pin	Connection
#1	X'tal
#2	GND
#3	X'tal
#4	GND

Internal connection (TOP VIEW)



#2 and #4 are connected to the cover. (Please connect to ground)



[1] Product Number / Product Name

(1-1) Product Number

X1E000251xxxx26 (Please contact Epson for details)

(1-2) Product Name (Standard Form)

FA-118T 24.00000MHz 12.0 +10.0-10.0 1 4

2 3

①Model ②Frequency ③Load capacitance (pF) ④Frequency tolerance (x10⁻⁶, +25 °C) In addition to the mentioned above specification items(① to ④), pleases specify the frequency vs. temperature characteristics.

[2] Absolute Maximum Ratings

ltem	Symbol		Rating value)	Unit	Note	
liem	Symbol	Min.	Тур.	Max.	Offic	Note	
Storage temperature range	T_stg	-40	-	+125	°C	Satisfy environmental characteristics specifications	

[3] Operating Conditions

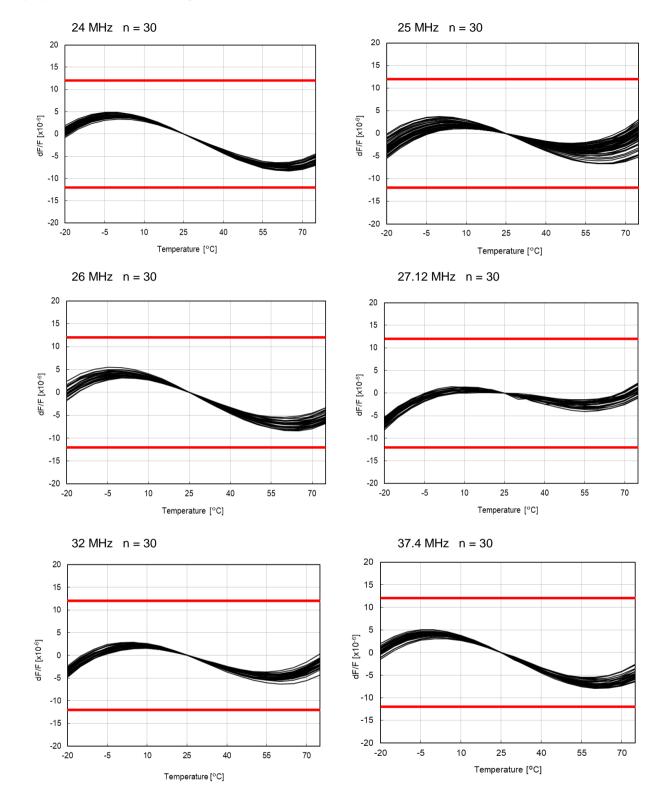
ltem	Symbol		Rating value	•	Unit	Note	
nem	Symbol	Min.	Тур.	Max.	Onit	Note	
Operating temperature range	T_use	-40	-	+85	°C		
Operating temperature range		-40	-	+105	-	Please contact Epson	
Level of drive	DL	1		200	μW	Recommended: 10 µW	

[4] Static Characteristics

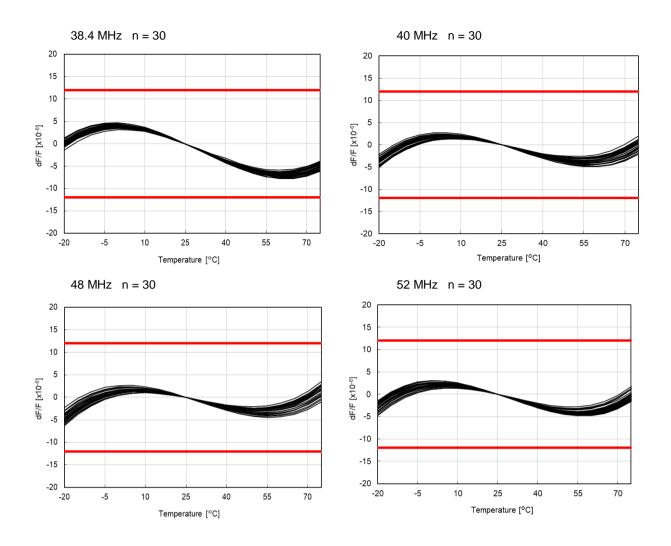
Item	Symbol	Specifications	Unit	Condition / Remarks
Nominal frequency range	f_nom	24.000 to 54.000	MHz	
Frequency tolerance (Standard)	f_tol	±10 / ±30	x10 ⁻⁶	T_use = +25 °C ± 3 °C DL = 100 μ W Does not include frequency aging Please contact Epson for requirements not listed in the specifications
Frequency vs. temperature characteristics (Standard)	f_tem	±12 / ±30	x10 ⁻⁶	Reference at $t_use = +25 \text{ °C} \pm 3 \text{ °C}$ -20 °C to $+75 °CPlease contact Epson forrequirements not listed in thespecifications$
Load capacitance	CL	6 to co	pF	Please specify
Motional resistance (ESR)	R1	Table 1.	Ω	π circuit IEC 60444-2 T_use = Operating temperature range DL = 100 μW
Shunt capacitance	C0	3.0 Max.	pF	
Frequency aging	f_age	±1 Max. / ±5 Max.	x10 ⁻⁶	T_use = +25 °C ± 3 °C

Table 1.

Frequency	R1
24 MHz <u><</u> f_nom < 32 MHz	200 Ω Max.
32 MHz <u><</u> f_nom < 36 MHz	100 Ω Max.
36 MHz <u><</u> f_nom <u><</u> 54 MHz	80 Ω Max.



[5] Example of Frequency Temperature Characteristics



[6] Marking Description

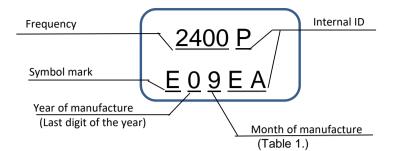
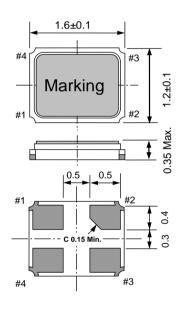
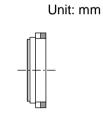


Table 1. Month of manufacture

Mont	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	Х	Y	Ζ

[7] Outline Drawing and Recommended Footprint





#4

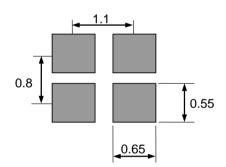
#1

Internal connection (TOP VIEW)

#2 and #4 are connected to the cover. (Please connect to ground)

#3

#2



Pin	Connection
#1	X'tal
#2	GND
#3	X'tal
#4	GND

Reference weight Typ.: 3 mg

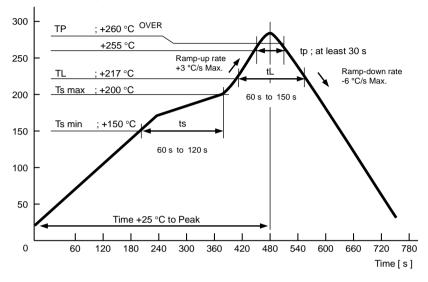
Terminal coating: Au plating

[8] Moisture Sensitivity Level

Parameter	Specification	Conditions
MSL	LEVEL1	JEDEC J-STD-020D.01

[9] Reflow Profile (JEDEC J-STD-020D.01)

Temperature [°C]



[10] Packing Information

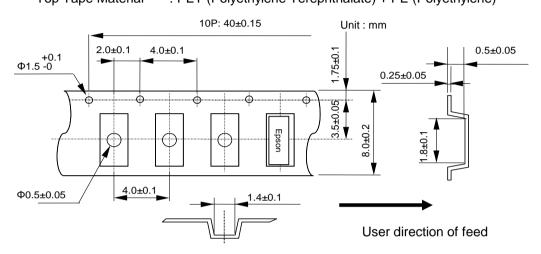
(1) Packing Quantity

The last two digits of the Product Number (X1E000251xxxx \underline{xx}) are a code that defines the packing quantity. The standard is "26" for a 6 000 pcs / Reel.

(2) Taping Specification

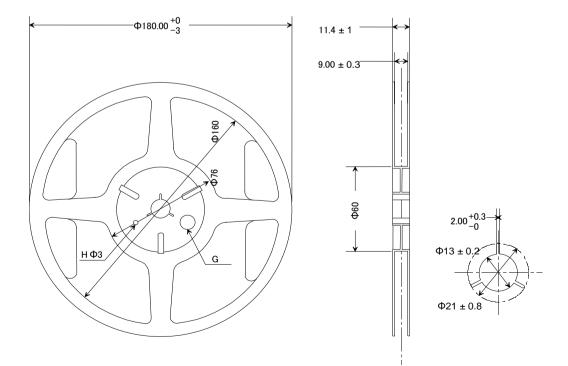
Subject to EAI-481, IEC 60286 and JIS C0806

(2-1) Tape Dimensions
 Carrier Tape Material : PS (Polystyrene)
 Top Tape Material : PET (Polyethylene Terephthalate) + PE (Polyethylene)



(2-2) Reel Dimensions

Center Material : PS (Polystyrene) Reel Material : PS (Polystyrene)



[11] Handling Precautions

Prior to using this product, please carefully read the section entitled "Precautions" on our Web site (https://www5.epsondevice.com/en/information/#precaution) for instructions on how to handle and use the product properly to ensure optimal performance of the product in your equipment. Before using the product under any conditions other than those specified therein,

please consult with us to verify and confirm that the performance of the product will not be negatively affected by use under such conditions.

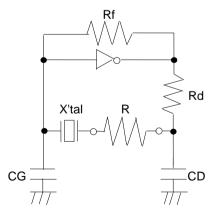
In addition to the foregoing precautions, in order to avoid the deteriorating performance of the product, we strongly recommend that you DO NOT use the product under ANY of the following conditions:

- 1. Max three (3) times re-flow is allowed. Its recommended to manually solder when not enough/no solder detected.(Using soldering iron at +350 °C Max × within 5 seconds)
- Avoid using the products if it received any excessive shocks and vibrations
 Crystal products may be damaged under some conditions during mounting if exposed to excess shock.
 Please set the mounting conditions to a slow mounting speed on the PCB to minimize shock as much as possible.
 Please review the conditions after the changed are made.
- 3. Keep the electrode wiring as short as possible to ensure normal oscillation.
- 4. Store the crystal products at normal temperature (+15 ° C to +35 ° C) and humidity (25 %RH to 85 %RH) Storing the crystal products under higher temperature or high humidity over one year may affect frequency stability or solderability.
- Contact Epson before use if the product has been stored outside the conditions mentioned above. 5. Ultrasonic equipment used for cleaning or bonding may deteriorate the characteristics of the product.
- Be sure to check in advance.6. In high humidity environment, dew condensation on the PCB board may cause malfunction such frequency shift or no oscillation.
- Applying excessive drive level to the crystal units may cause deterioration of characteristics or damage.
 Design and test the circuit so that the proper drive level is maintained.
- 8. The characteristic such as frequency, etc. may differ from your measurement depending on the measurement method or conditions.

Contact Epson for any questions.

- 9. In order to avoid malfunction by other signal lines, design pattern other signal lines away from the product. and in case of multi-layered PCB board, do not lay out other signal lines under. If shielding with GND is required, shield the surface farthest from the oscillation circuits.
- 10.Ensure adequate negative resistance is allocated in the oscillation circuit, otherwise oscillation startup time may increase or no oscillation may occur. In order to avoid this, provide enough negative resistance that is 5 time the motional resistance(R1)
- Aging specifications are estimated from environmental reliability tests and expected frequency variation over time. They do not provide a guarantee of aging over the product lifecycle.
- 12. Should any customer use the product in any manner contrary to the precautions and/or advice herein, such use shall be done at the customer's own risk.

How to check the negative resistance.



- 1) Insert a pure resistance R in series with the X'tal.
- 2) Adjust R and find the maximum R value that starts oscillation.
- 3) Check the value of R in the oscillation state of 2).
 Negative resistance of the circuit |-R| =
 R + Series resistance value R1 of the X'tal
- 4) Negative resistance |-R| guideline: |-R| > R1 Max. x 5

PROMOTION OF ENVIRONMENTAL MANAGEMENT SYSTEM CONFORMING TO INTERNATIONAL STANDARDS

At Seiko Epson, all environmental initiatives operate under the Plan-Do-Check-Action (PDCA) cycle designed to achieve continuous improvements. The environmental management system (EMS) operates under the ISO 14001 environmental management standard. All of our major manufacturing and non-manufacturing sites, in

Japan and overseas, completed the acquisition of ISO 14001 certification.

WORKING FOR HIGH QUALITY

In order provide high quality and reliable products and services than meet customer needs, Seiko Epson made early efforts towards obtaining ISO9000 series certification and has acquired ISO9001 for all business establishments in Japan and abroad. We have also acquired IATF 16949 certification that is requested strongly by major manufacturers as standard.

Explanation of marks used in this datasheet

ISO 14000 is an international standard for environmental management that was established by the International Standards Organization in 1996 against the background of growing concern regarding global warming, destruction of the ozone layer, and global deforestation.

IATF 16949 is the international standard that added the sector-specific supplemental requirements for automotive industry based on ISO9001.

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